



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP ProBook 440 G8
HP ZHAN 66 Pro 14 G4 Notebook PC
HP ProBook 440 G8 Notebook PC / HSN-Q28C-4

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	
Batteries, excluding Li-Ion batteries.	All types including standard alkaline, coin or button style batteries	
Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)	Battery(ies) are attached to the product by (<i>check all that apply with an "x" inside the "[]"</i>): [3] screws [X] snaps [1] adhesive [X] other. Explain <u>X</u> NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries NA	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LED	
Cathode Ray Tubes (CRT)	NA	
Capacitors / condensers (Containing PCB/PCT)	NA	
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	NA	
External electrical cables and cords	DC Cable for External Power Supply	
Gas Discharge Lamps	NA	
Plastics containing Brominated Flame Retardants	NA	0

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Last revalidation date 09-May-2018

HPI instructions for this template are available at [EL-MF877-01](#)

Item Description	Notes	Quantity of items included in product
weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. NA	0
Components and waste containing asbestos	NA	0
Components, parts and materials containing refractory ceramic fibers	NA	0
Components, parts and materials containing radioactive substances	N	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
T8 Screwdriver	#T8
Screwdriver	#T1

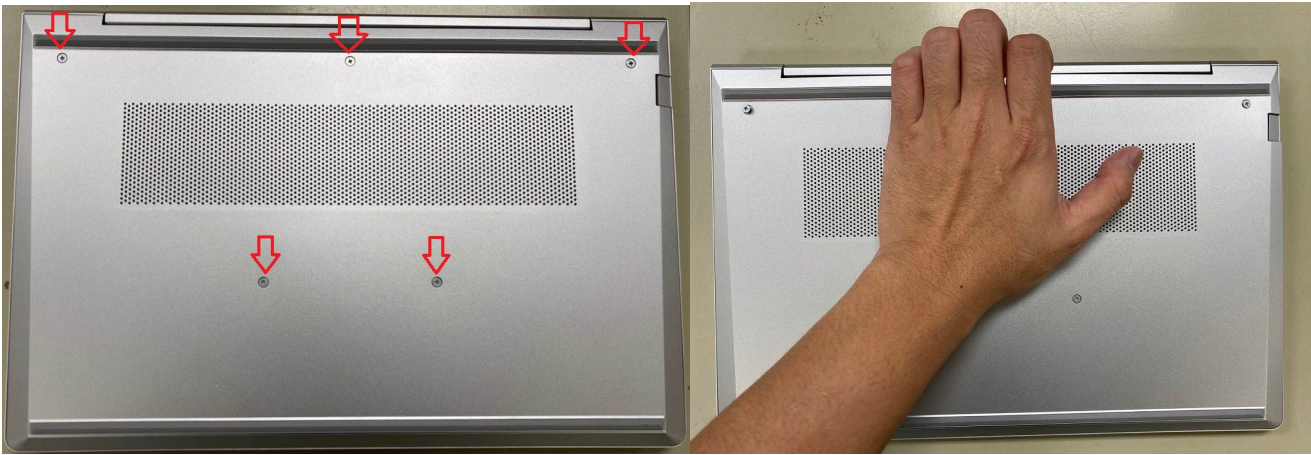
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Use screwdriver to release base cover #1 screw 5PCS, and disassemble base cover from hinge side.
2. Use screwdriver to release battery screw 4 PCS and release Battery.
3. Use screwdriver to release main board #1 screw 6 PCS
4. Release below cable: Speaker cable, DC-IN Cable, HDD cable, Finger Printer cable, backlight cable, TP cable, SD card cable, KB Cable, Power board cable, EDP cable, WWan antenna cable, Wlan antenna cable. And Disassemble Type-C BKT, RJ-45. Final step release main board
5. release hinge screw with screwdriver
6. Set Hinge UP to 90 degree and release hinge up

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

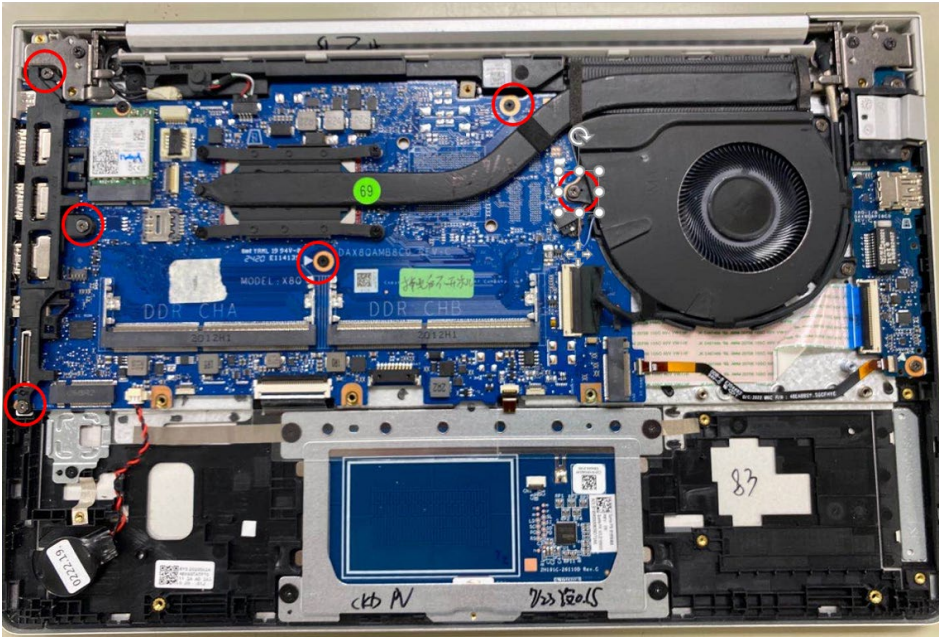
3.21 Use screwdriver to release base cover #1 screw 5PCS, and disassemble base cover from hinge side



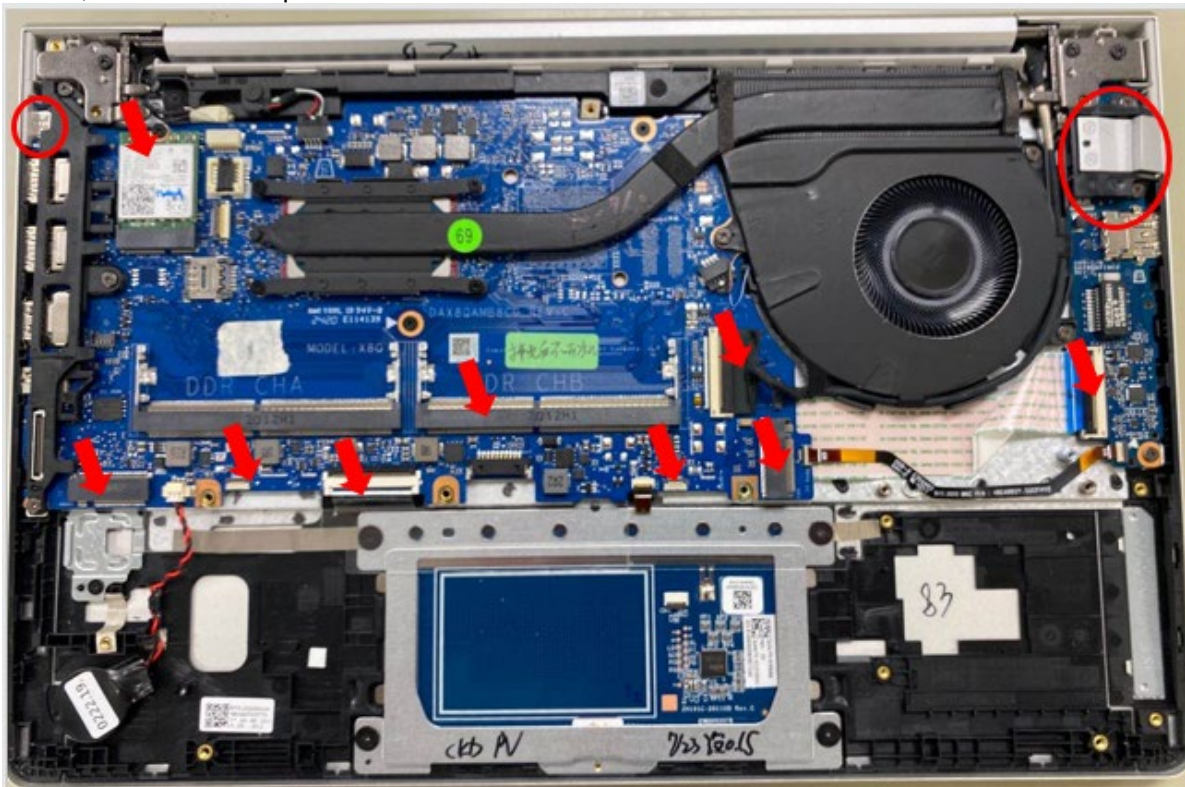
3.22 Use screwdriver to release battery screw 4 PCS and release Battery.



3.23 Use screwdriver to release main board #1 screw 6 PCS



3.24 Release below cable: Speaker cable, DC-IN Cable, HDD cable, Finger Printer cable, backlight cable, TP cable , SD card cable, KB Cable, Power board cable ,EDP cable ,WWan antenna cable, Wlan antenna cable. And Disassemble Type-C BKT, RJ-45. Final step release main board



3.25 release hinge screw with screwdriver



3.26 Set Hinge UP to 90 degree and release hinge up